| | Form 1595 1-31-92 | RECO |
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ORDATION

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| | 4-12-04 PATENTS ONLY | - • 1 | 237 | | |
|--|---|---|----------------|--|--|
| | To the Honorable Assistant Commissioner for Patents: Please record the attached | | | | |
| | original documents or | T | 22 | | |
| 1. | Name of conveying party(ies): | 2. Name/address of receiving Party(ies): | - | | |
| ŀ | Chien-Hsing Lee, | | | | |
| | Chin-Hsi Lin, | Solid State System Co., Ltd. | | | |
| | · · · · · · · · · · · · · · · · · · · | | | | |
| <u> </u> | Jhyy-Cheng Liou | 5F-1, No. 22, Taiyuen Street, Jubei | i | | |
| 3. | Nature of conveyance: | City, Hsinchu, Taiwan 302, R.O.C. | | | |
| | ☐ Merger ☐ Security Agreement ☐ Other | ony, risinona, raiwan 302, re.o.e. | • | | |
| | ☐ Change of Name ☐ Reassignment | | | | |
| | | Add'l names of receiving parties | | | |
| 4. | Date(s) of execution: April 6, 2004. | Attached? Yes No | | | |
| | • | | | | |
| 5. | Application number(s) or patent number(s): | 11 82 2/180 | | | |
| | • | 10020477 | | | |
| | If this documents is being filed together with a new application, the | | | | |
| | execution date of the application is A | <u> April 6, 2004</u> . | | | |
| | | | | | |
| | A. Patent Application No. (s) | B. Patent No. (s) | | | |
| ļ | | | | | |
| | | | | | |
| | Additional numbers attached | ? □ Yes ☒ No | | | |
| 6. | Name and address of party to whom | 7. Total No. of applications and patents | s | | |
| | Correspondence concerning document | involved: | | | |
| | should be mailed: | OME(I) | | | |
| | should be maried. | ONE(1) | | | |
| | T. C. Detrook of | 8. Total fee (37 CFR §3.41): <u>\$40.00</u> | | | |
| | J.C. Patents, Inc. | | | | |
| | 4 Venture, Suite 250 Irvine, CA 92618 | Lifeiosed | | | |
| | (949) 660-0761 | ☐ Charge to Acct. No | | | |
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| and correct and any attached copy is a true copy of the original document. | | | | | |
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| | _ | | | | |
| | Jiawei Huang | 11 // 12/2 | - | | |
| | | Data - 12/2001 | | | |
| | | / Date / | | | |
| Kegi | istration No. 43,330 | | | | |

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FC:8021 40.00 OP

> **PATENT REEL: 015211 FRAME: 0372**

ASSIGNMENT

WHEREAS.

1. Chien-Hsing Lee

2. Chin-Hsi Lin

3. Jhyy-Cheng Liou

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: CIRCUIT LAYOUT AND STRUCTURE FOR A FLASH MEMORY

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Solid State System Co., Ltd.

of 5F-1, No. 22, Taiyuen Street, Jubei City, Hsinchu, Taiwan 302, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

REEL: 015211 FRAME: 0373

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Date:

Chien - Hsing Lee
Signature:

April 6, 2004

Sole or First Joint Inventor: Chien-Hsing Lee

Chin Hei Kin

April 6, 2004

Second Joint Inventor(if any): Chin-Hsi Lin

Signature: Jay

RECORDED: 04/12/2004

April 6, 2004
Date:

Third Joint Inventor(if any): Jhyy-Cheng Liou